



X-832-050 A/B

Shin-Etsu Silicones of America, Inc.
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Product Description

X-832-050 is a general purpose potting gel exhibiting excellent electrical properties and environmental stability. X-832-050 has a fast low temperature cure making it a good candidate for high speed, automated, no energy processing

Product Features

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- 100:100 mix ratio
- Fast gel time of 5 min
- Room temperature cure
- Excellent electrical properties

Typical Properties

Type	Potting Gel
Cure Type	Addition
One/Two Component	Two
Color	Transparent
Density @ 23C (g/cm ³)	0.97
Viscosity Mixed (cps)	750.00
Mix Ratio by weight	100:100
Cure Conditions	1Hr @ 25°C
Snap Time (min)	5
Penetration (1/10mm)	70
Volume Resistivity (TΩ·m)	2 x 10 ¹⁵
Dielectric Strength (kV/mm)	20
Dielectric Constant	2.7 @ 60Hz
Dielectric Dissipation Factor	2 x 10 ⁻⁴
Thermal Conductivity (W/m·K)	0.20
Usable Temperature Range (C)	-35°C to +200°C

Note: Values are not for specification purposes.

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